

RoHS/Green Certificate for homogeneous wafers from TSMC

Doc no: QI-21 Rev: D01

Revision History

| Rev. | Description of Change | Reason for Change |
|------|---------------------------------------|-----------------------------------|
| A00 | Initial Release | Customer request |
| B00 | Replace certificate with 2008 version | Keep current per RoHS directive |
| C00 | Replace certificate with 2009 version | Includes REACH SVHC list elements |
| C01 | Remove blank pages | Correct formatting error |
| D00 | Replace certificate with 2010 version | Keep current per RoHS directive |
| D01 | Revised 3.1 | Removed SGS report as example |



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1.0 Purpose and Scope

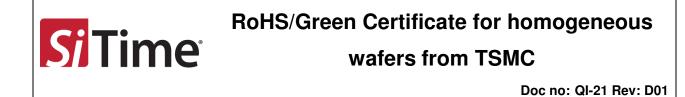
- 1.1 Purpose: To demonstrate RoHS/Green compliance per QI-1 as applicable to homogeneous substances and to declare no substances of very high concern (SVHC) per REACH requirements.
- 1.2 Scope: All products manufactured by and for SiTime using TSMC wafers.

2.0 Reference Documents

- 2.1 Industry Standards
 - 2.1.1 EU RoHS Directive 2002/95/EC and amendments
- 2.2 Internal References
 - 2.2.1 QI-1 SiTime green partner and RoHS/Green Compliance

3.0 Information

- 3.1 The list of SGS report of analysis demonstrating RoHS and Green compliance of the homogeneous materials used for wafer from TSMC are attached (Table-1)
- 3.2 The SGS analysis reports for the homogeneous materials are received from the supplier (updated every year) and reviewed and maintained at SiTime.
- 3.3 Actual SGS reports can be obtained from sales support by request. Contact SiTime sales support at <u>salessupport@sitime.com</u>
- 3.4 As per industry standard practice (JEDEC Standard JESD46), the customer notification will be done when any major change in the material composition is implemented which affects form, fit and function. No annual updating will be done to this document. The updates to this document will be done only when:
- 3.4.1 There is any change in the material contents of the package
- 3.4.2 The regulation changes dictate that new analysis be done for compliance



4.0 Homogeneous Material Content Tables

Table-1 Homogeneous Material List Contained in wafer - TSMC

| Homogeneous Material | Material Name/Model | Supplier | SGS Report |
|-------------------------|---------------------|----------|------------|
| CMOS Die | Silicon | TSMC | ٧ |